

500V PNP HIGH VOLTAGE TRANSISTOR IN SOT23


Description

This Bipolar Junction Transistor (BJT) has been designed to meet the stringent requirements of Automotive Applications.

Features

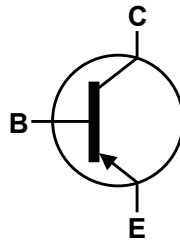
- $BV_{CEO} > -500V$
- $I_C = -150mA$ high Continuous Collector Current
- I_{CM} Up to 500mA Peak Pulse Current
- Excellent h_{FE} Characteristics up to $I_C = 100mA$
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

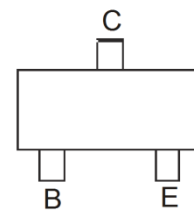
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per
MIL-STD-202, Method 208 
- Weight 0.008 grams (approximate)



Top View



Device Symbol



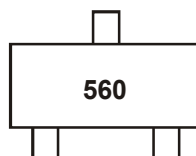
Top View
Pin-Out

Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FMMT560QTA	Automotive	560	7	8	3,000
FMMT560QTC	Automotive	560	13	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

Marking Information



560 = Product Type Marking Code

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-500	V
Collector-Emitter Voltage	V_{CEO}	-500	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	I_C	-150	mA
Peak Pulse Current	I_{CM}	-500	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

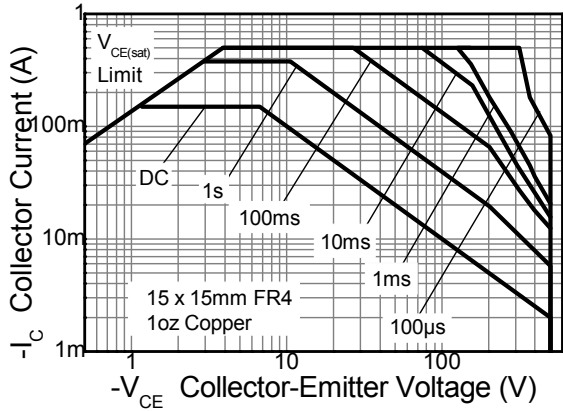
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	500	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	250	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead (Note 7)	$R_{\theta JL}$	194	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

ESD Ratings (Note 8)

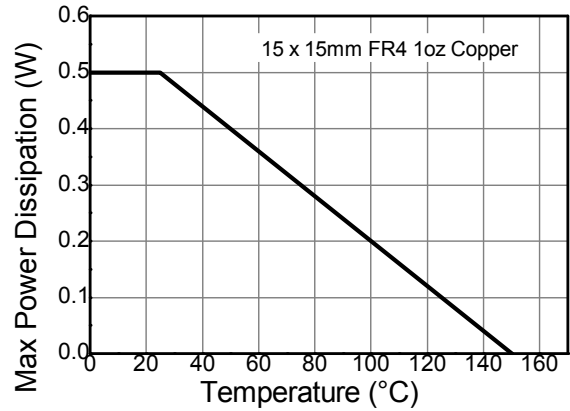
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 15mm x 15mm 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

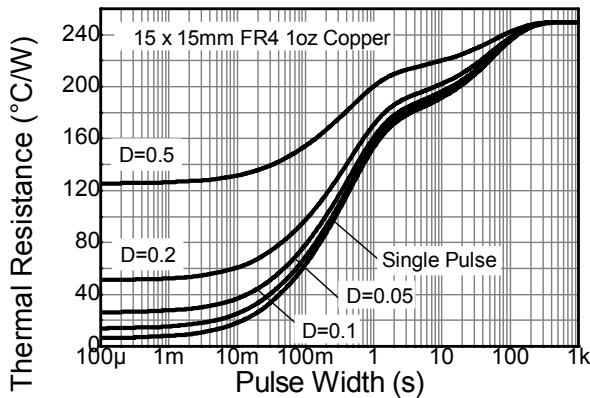
Thermal Characteristics and Derating Information



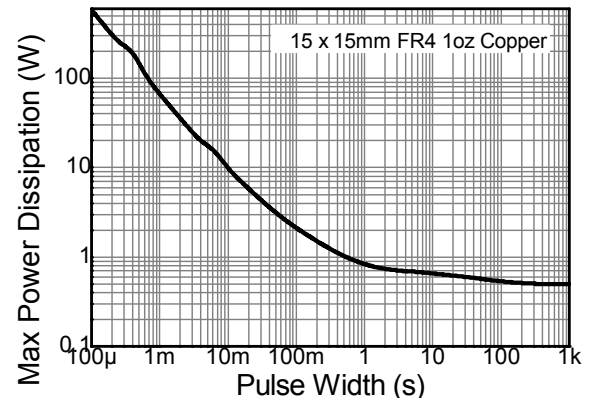
Safe Operating Area



Derating Curve



Transient Thermal Impedance



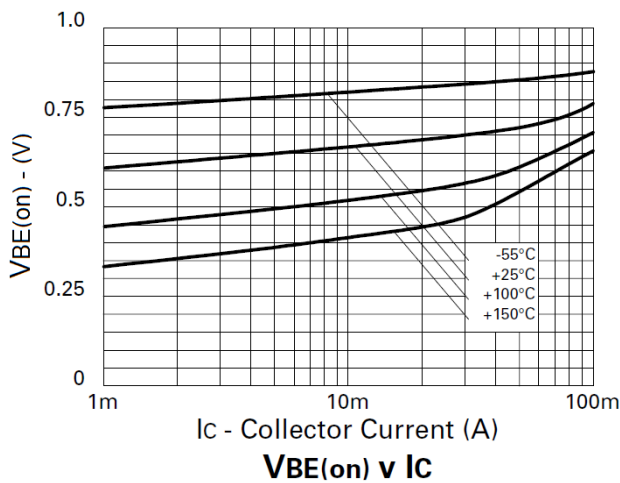
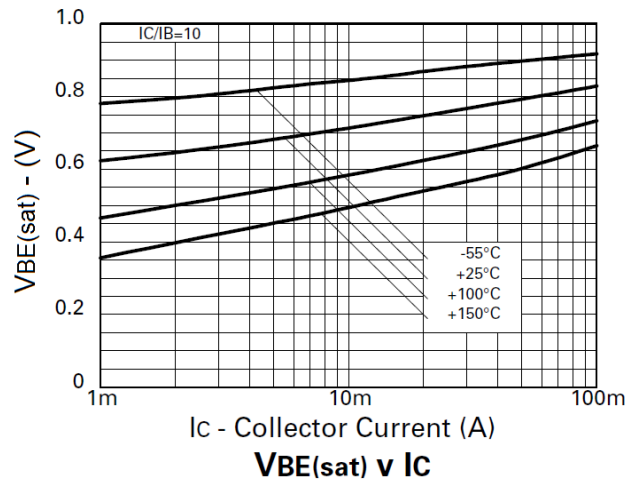
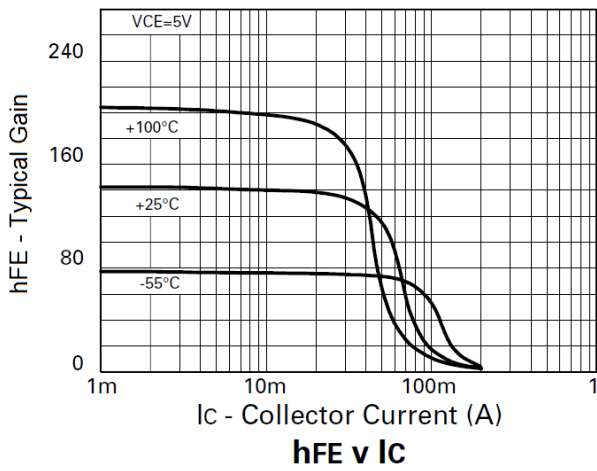
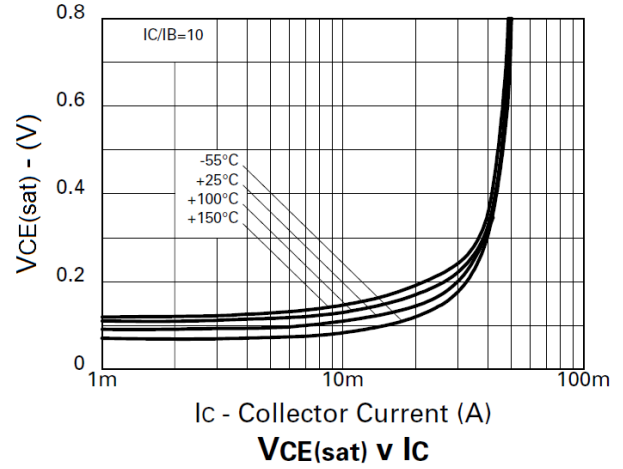
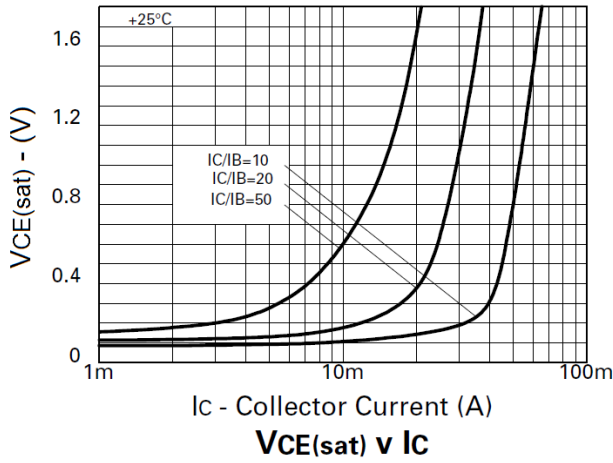
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-500	—	—	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-500	—	—	V	I _C = -1mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	—	—	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	—	—	-100	nA	V _{CB} = -500V
Emitter Cutoff Current	I _{EBO}	—	—	-100	nA	V _{EB} = -5V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	100 80 —	— — 15	300 300 —	—	I _C = -1mA, V _{CE} = -10V I _C = -50mA, V _{CE} = -10V I _C = -100mA, V _{CE} = -10V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	—	—	-200 -500	mV	I _C = -20mA, I _B = -2mA I _C = -50mA, I _B = -10mA
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	—	—	-0.9	V	I _C = -50mA, I _B = -10mA
Base-Emitter Turn-On Voltage (Note 9)	V _{BE(on)}	—	—	-0.9	V	I _C = -50mA, V _{CE} = -10V
Output Capacitance	C _{obo}	—	—	8	pF	V _{CB} = -20V, f = 1MHz
Transition Frequency	f _T	60	—	—	MHz	V _{CE} = -20V, I _C = -10mA, f = 50MHz
Turn-On Time	t _{on}	—	110	—	ns	V _{CE} = -100V, I _C = -50mA,
Turn-Off Time	t _{off}	—	1.5	—	μs	I _{B1} = -5mA, I _{B2} = 10mA

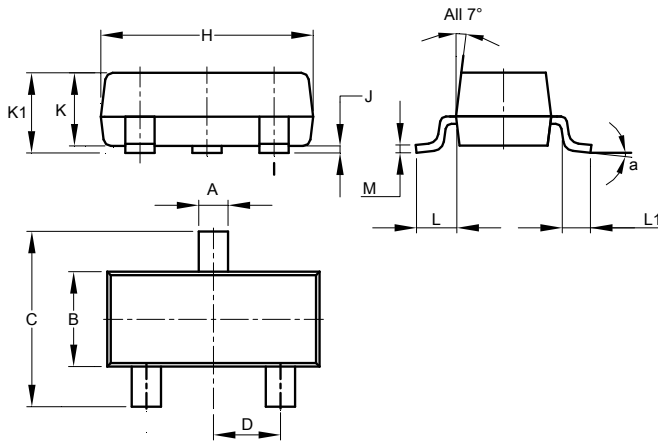
Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



Package Outline Dimensions

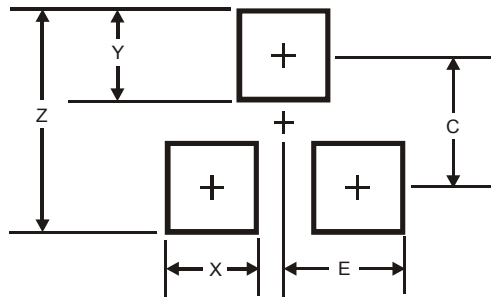
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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